

TEST SERVICES



A Member of the Hong Leong Group

Complete Manufacturing Services

Carsem provides a full range of test solutions and services to over 80% of its assembly customer base for their RF, Mixed-Signal, Digital and Power device families.



Total Dedicated Test Floor Space in Excess of 110,000 Sq. Ft. (10,200 Sq. M)

- Carsem Malaysia = 100,000 Sq. Ft.
- Carsem Suzhou / China = 25,100 Sq. Ft.
- Full Test Development Lab
- RF Faraday Cage Enclosure
- Skills Training and Development Facility



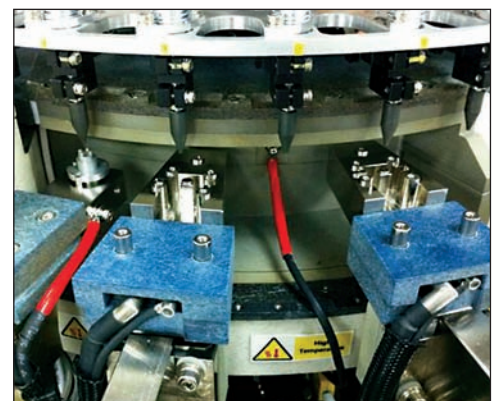
Newly Expanded Wafer Probe Area

- Up to 8" Wafers with Hot Chuck Capability
- Below 4 mils Thin Wafer Probe Capability
- Bumped Die Vertical Probe Capability
- Inkless or Off-Line Inking Capability
- Limited In-House Probe Card Repair Services
- Probe Equipment Supported: TEL P8XL, KLA, EG2080, TSK



Over 600 Test Systems

- Verigy/LTX/Credence: ASL1000/3000/3000RF, FUSION CX, MX-C, PAX RF
- Teradyne/Eagle: ETS-88, ETS-200T/FT, ETS-300, ETS-364
- Teradyne: MicroFlex, Catalyst (RF), A585/A575
- Amida: 3001
- Chroma: 3650



Complete Handler and Socket Solutions

- Light Sensors, Temperature Sensors, MEMS, Tri-Temp, (Film Frame) Strip Test
- Handlers: SRM, Rasco, Multitest, Ismecca, Hontech, Tesec, Pentamaster, Fastech
- Sockets: (Kelvin & Plunge-to-Board) Johnstech, ECT, NHK, Rika Denshi, MJC, Synergetix, Antares, Shin-Etsu, Parison
- In-Line Laser Socket Cleaning

Additional Services Include:

Post Test Laser Mark, Dry Pack, Tape & Reel (package or die), Bar-coding, Finished Goods Inventory, Drop Ship



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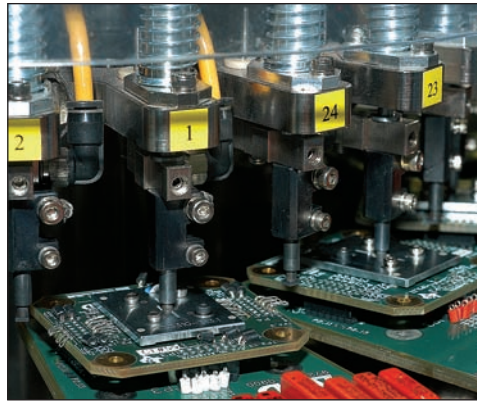
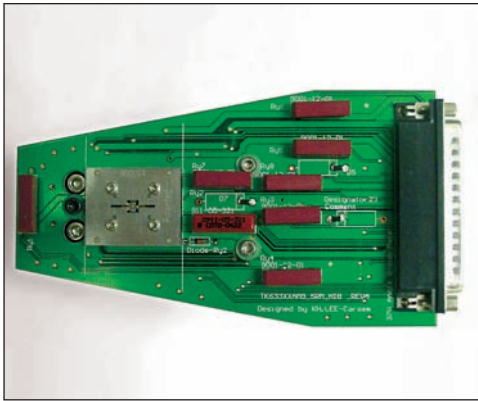
Value Added Engineering Support Services

In addition to our comprehensive manufacturing services, Carsem's dedicated test engineering staff provides complete test program/hardware development services, program conversions, new process development, as well as complete product engineering support including program debug, temperature characterization, product correlation, process improvement, low yield analysis and cost-of-test reduction.



Test Program and Hardware Development

- RF Calibration, Tuning & Instrumentation Lab
- Process/Systems Methodology for Development of Software and Hardware Solutions
- Efficient Project Milestone Tracking & Reporting
- Focus on Fastest Time to Market with Lowest Cost of Ownership
- Turnkey Tester, Handler, Load Board and Socket Solutions with Optimum Throughput
- Expertise in Mixed-Signal, Analog, Power Management, Digital and RF Devices



Product Experience

- **RF:** Bluetooth™ Modules, WiFi Devices, Low Noise and Power Amplifiers, Switches and Filters, Transceivers
- **Power Management:** Voltage Regulators, DC-DC Converters, Integrated MOSFETs, Diodes, Comparators, LED Drivers
- **Digital/Logic/Memory:** Bus Switches, Logic Gates, Add-on Memory, Clocks
- **Analog Mixed-Signal:** Audio/Video, Converters, Sensors, Precision References
- **MEMS/WLCSP:** Proximity Sensors, 3-axis digital compass, Wireless Power IC

Product Engineering Support

- Test Time Reduction and Enhancements
- Single to Multi-site and Strip Test Conversions
- Program Debugging and Low Yield Analysis
- Full Correlation and Qualification Services
- Product Failure Analysis (X-Ray, Decap)
- Consigned Equipment Enhancements and OEE Monitoring
- Automated Process Monitoring

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